



SOT778-7

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 6 mm x 6 mm x 0.85 mm

1 June 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package type industry code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	22-4-2016
Manufacturer package code	SOT778

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A ₂	package height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	48	-	



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2. Package outline

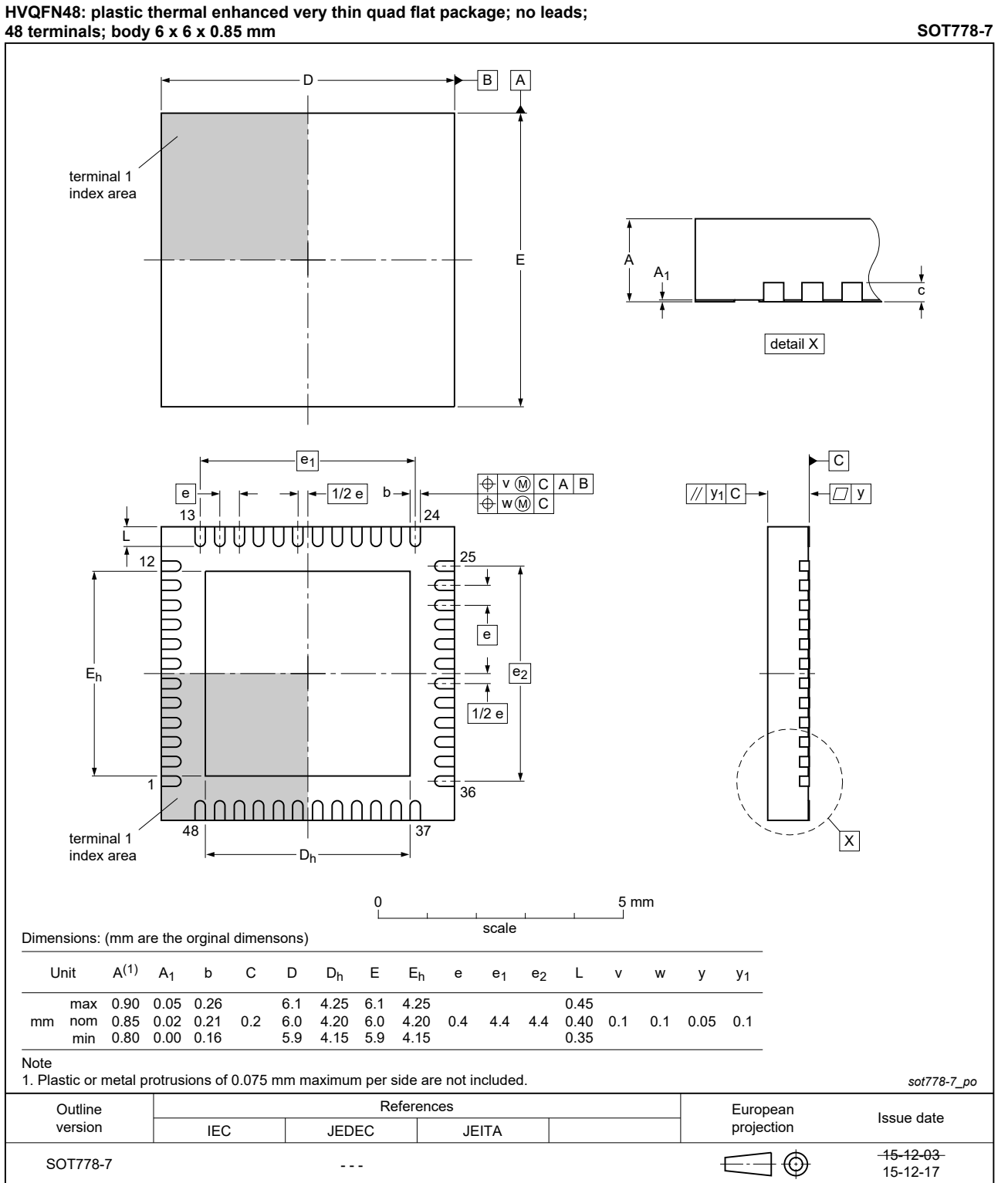


Fig. 1. Package outline HVQFN48 (SOT778-7)

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3. Soldering

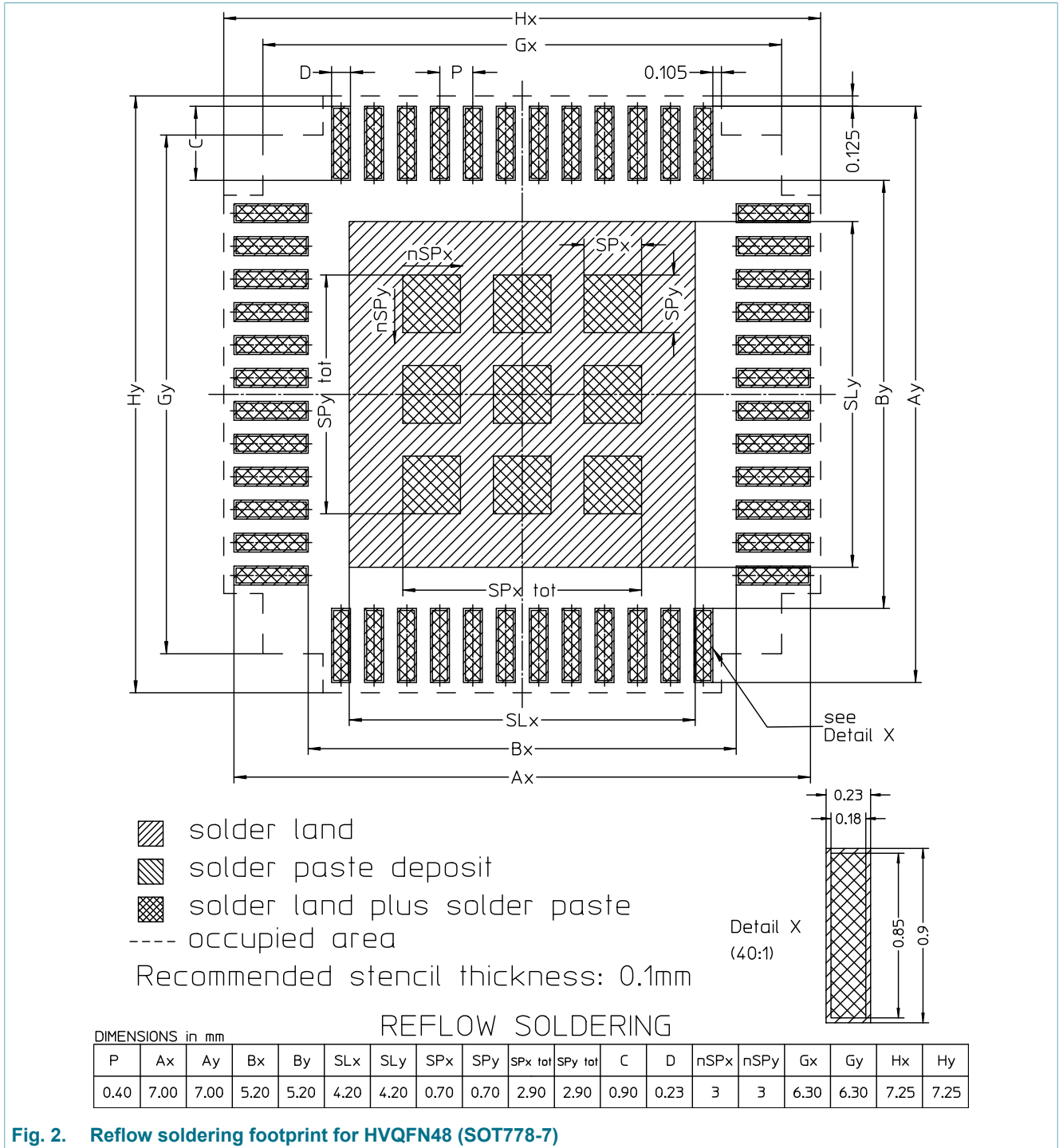


Fig. 2. Reflow soldering footprint for HVQFN48 (SOT778-7)

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4. Legal information

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